

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ATTY.'S DOCKET: CHIU=13A

In re Application of:	)	Art Unit: 2815
	)	
CHIU, Wen-Wen	)	Examiner: --
	)	
Appln. No.: Not yet assigned	)	Washington, D.C.
Continuation of 10/033,932	)	
	)	
Filed: Evendate herewith	)	Confirmation No. --
	)	
For: IC CHIP PACKAGE	)	January 27, 2004
	)	

COMMUNICATION

Honorable Commissioner for Patents  
2011 South Clark Place  
Crystal Plaza Two, Lobby, Room 1B03  
Arlington, VA 22202

Sir:

The attached continuation application presents claims that differ from those of the parent application and that have been drafted to clearly define a contribution of the invention over the prior art.

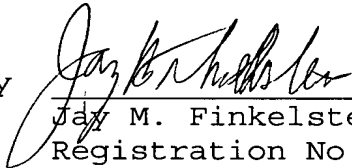
The reference relied upon during examination of the parent application, U.S. patent no. 6,317,326, shows, in figure 2b, a spacer in the form of a ring 226. Unlike that disclosed in the reference, the spacer according to the present invention, and now defined in application claim 1, is composed of two columns, resulting in a spacer having a lower material cost and occupying less space. Thus, when cutting a

circuit board according to the present invention having multiple-chip modules, it is possible to cut the columns shared by adjacent modules, as shown in the attached drawing, and to retain the remaining occupied areas of the modules.

Thus, the claims of the present application clearly distinguish patentably over that reference.

Respectfully submitted,

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